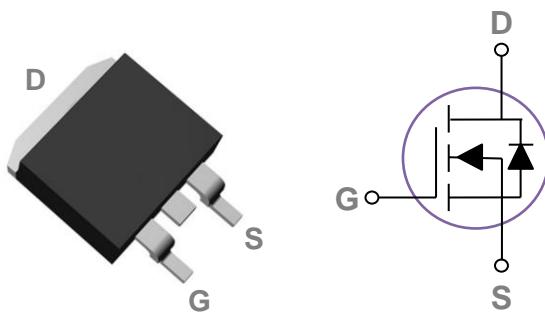


### General Description

These N-Channel enhancement mode power field effect transistors are using super junction MOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO263 Pin Configuration



BVDSS	RDS(ON)	ID
650V	190mΩ	20A

### Features

- 650V,20A, RDS(ON) =190mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- PFC Power Supply Stages
- Motor Control
- DC-DC Converters
- Adapter

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	650	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	20	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	12.5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	80	A
EAS	Single Pulse Avalanche Energy	420	mJ
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	160	W
	Power Dissipation – Derate above 25°C	1.28	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	0.78	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=1\text{mA}$	650	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=650\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=520\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125\text{ }^{\circ}\text{C}$	---	---	10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 30\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$ , $I_D=10\text{A}$	---	160	190	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D = 250\mu\text{A}$	2	3	4	V

**Dynamic and switching Characteristics**

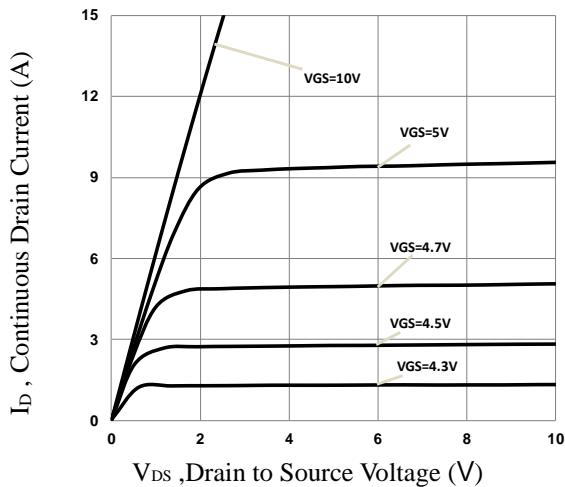
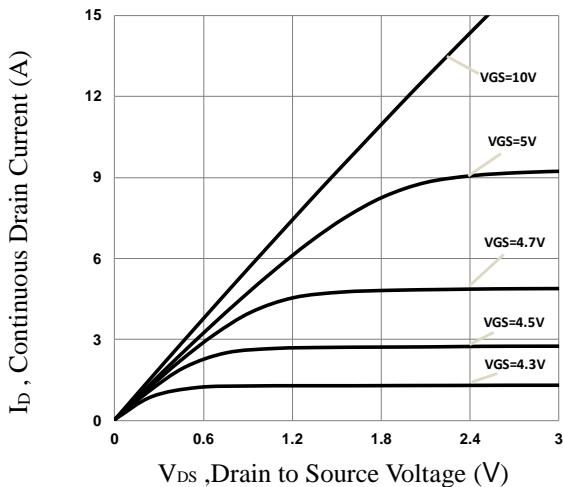
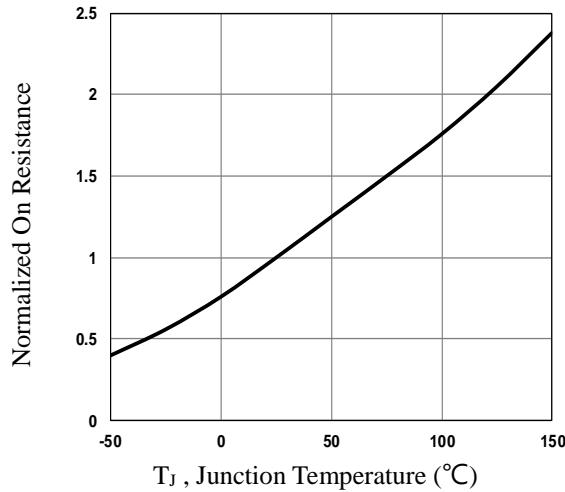
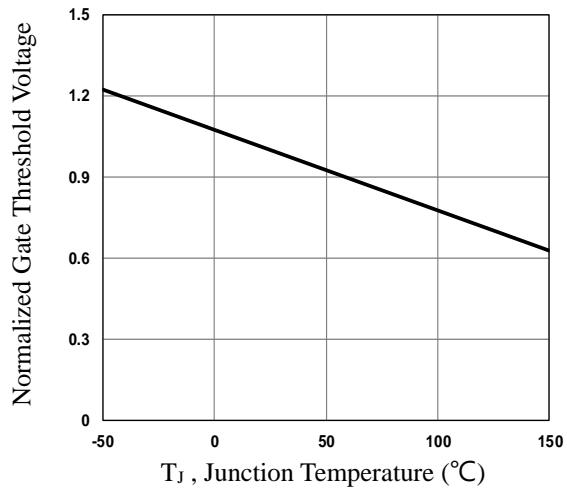
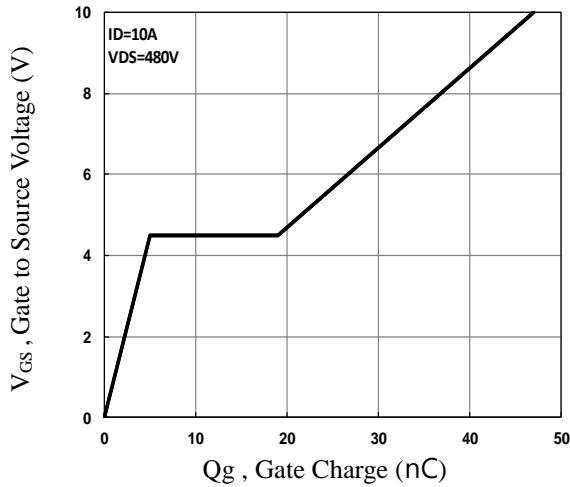
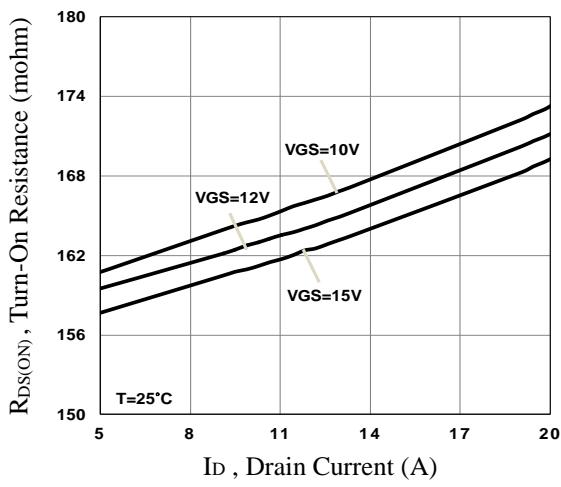
$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=480\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=10\text{A}$	---	47	70	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	5	8	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	14	21	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DS}=480\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=25\Omega$ $I_D=10\text{A}$	---	32	48	ns
$T_r$	Rise Time <sup>2,3</sup>		---	73	110	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	146	220	
$T_f$	Fall Time <sup>2,3</sup>		---	47	70	
$C_{iss}$	Input Capacitance	$V_{DS}=100\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	1400	2100	pF
$C_{oss}$	Output Capacitance		---	55	85	
$C_{rss}$	Reverse Transfer Capacitance		---	1.3	4.6	
$R_g$	Total Gate Charge <sup>2,3</sup>	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $F=1\text{MHz}$	---	8	---	$\Omega$

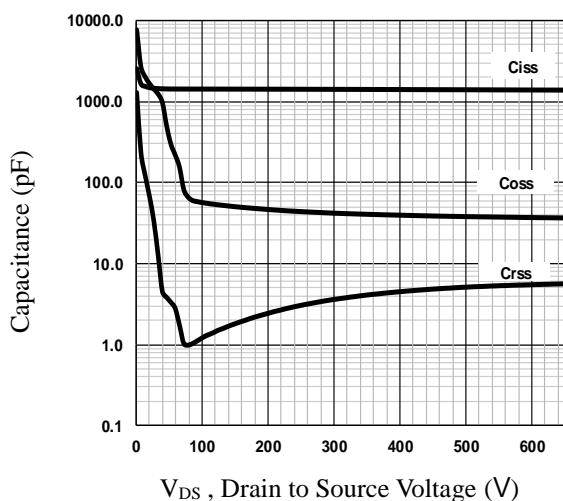
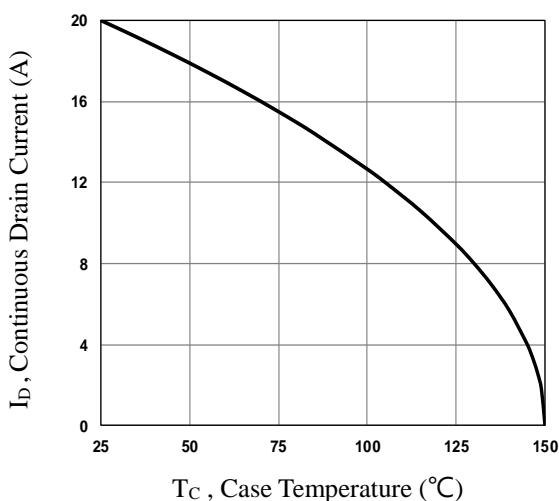
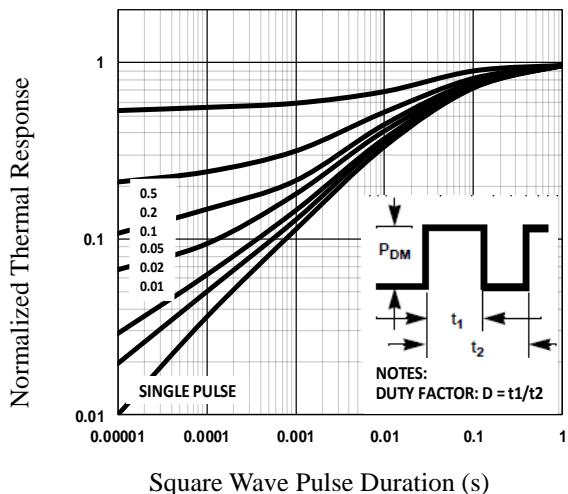
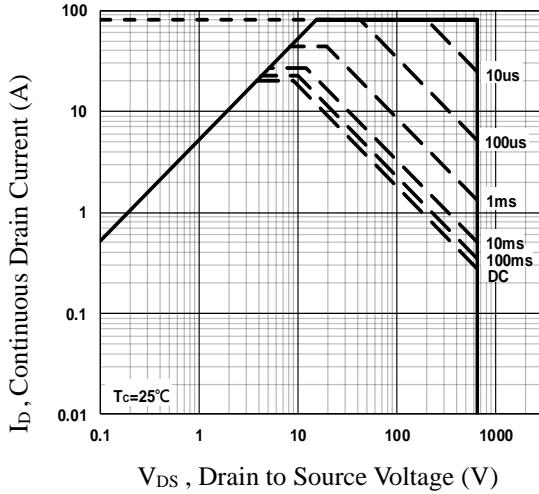
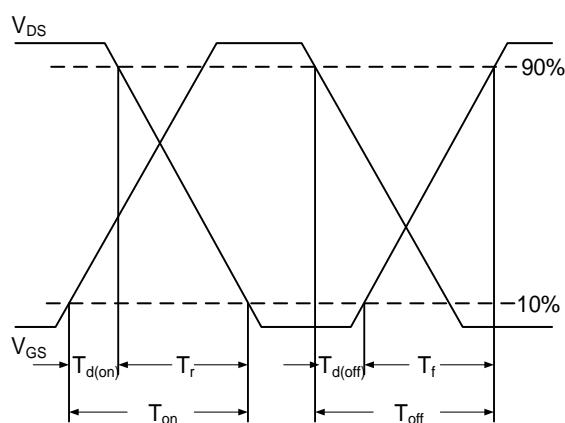
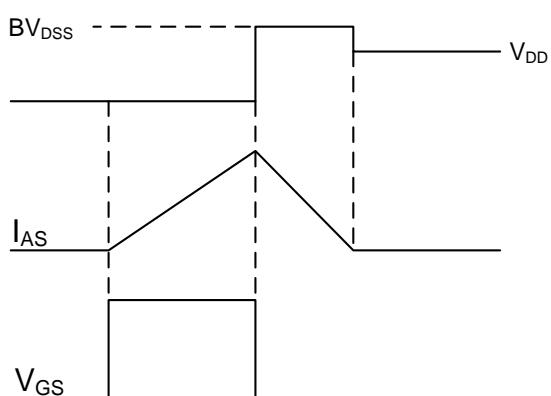
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	20	A
$I_{SM}$	Pulsed Source Current		---	---	40	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=10\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_R=400\text{V}$ , $I_s=10\text{A}$ $di/dt=100\text{A}/\mu\text{s}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	310	---	ns
$Q_{rr}$	Reverse Recovery Charge		---	4.4	---	$\mu\text{C}$

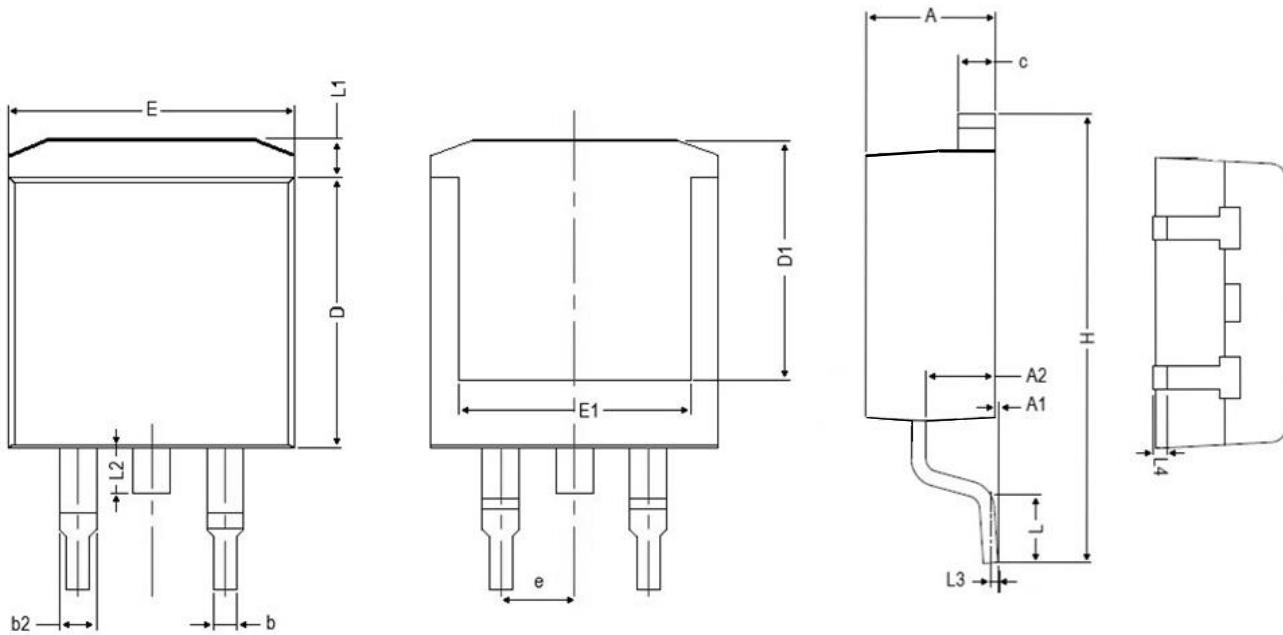
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.


**Fig.1 Typical Output Characteristics**

**Fig.2 Typical Output Characteristics**

**Fig.3 Normalized RDSON vs.  $T_J$** 

**Fig.4 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.5 Gate Charge Characteristics**

**Fig.6 Turn-On Resistance vs.  $I_D$**


**Fig.7 Capacitance Characteristics**

**Fig.8 Continuous Drain Current vs.  $T_c$** 

**Fig.9 Normalized Transient Impedance**

**Fig.10 Maximum Safe Operation Area**

**Fig.11 Switching Time Waveform**

**Fig.12 EAS Waveform**

## TO263 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	4.850	4.200	0.191	0.165
A1	0.300	0.000	0.012	0.000
A2	2.900	2.200	0.114	0.087
b	0.950	0.700	0.037	0.028
b2	1.700	1.000	0.067	0.039
c	1.450	1.150	0.057	0.045
D	9.500	8.350	0.374	0.329
D1	9.150	6.400	0.360	0.252
E	10.500	9.600	0.413	0.378
E1	8.900	6.850	0.350	0.270
e	2.540 BSC		0.100 BSC	
H	15.900	14.600	0.626	0.575
L	2.800	1.700	0.110	0.067
L1	1.700	1.050	0.067	0.041
L2	2.100	1.300	0.083	0.051
L3	0.250 BSC		0.010 BSC	
L4	0.750	0.200	0.030	0.008